

Examine & Gps

AN 2000:37783 HCAPLUS
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TI Lead-free solders
IN Matsumoto, Kazuo; Muraoka, Naoki; Omoto, Takahiko; Ozaki, Masakazu
PA Ishikawa Kinzoku K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 17 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|---|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | JP 2000015476 | A2 | 20000118 | JP 1998-182070 | 19980629 |
| AB | Sn alloys contg. Ag 0.5-3.5, Bi 0.5-10.0, Cu 0.1-1.0, P 0.001-0.01 wt.% and microalloyed with (a) Ni 0.001-0.01, (b) Ge 0.005-0.05, (c) Te 0.001-0.01 and Ga 0.01-0.1, or (d) Co 0.001-0.01 and/or Cr 0.005-0.05 wt.% are claimed as solders. The solders are esp. useful for accurate mounting of semiconductor chips, etc. on circuit substrates. | | | | |